

## / Descriptions

Silicon NPN transistor in a TO-92(R) Plastic Package.

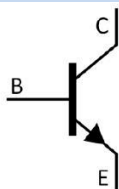
## / Features

High voltage, high current, excellent  $h_{FE}$  linearity, low noise, complementary to ED1602.

## / Applications

Audio frequency amplifier, driver stage amplifier applications.

## / Equivalent Circuit



## / Pinning



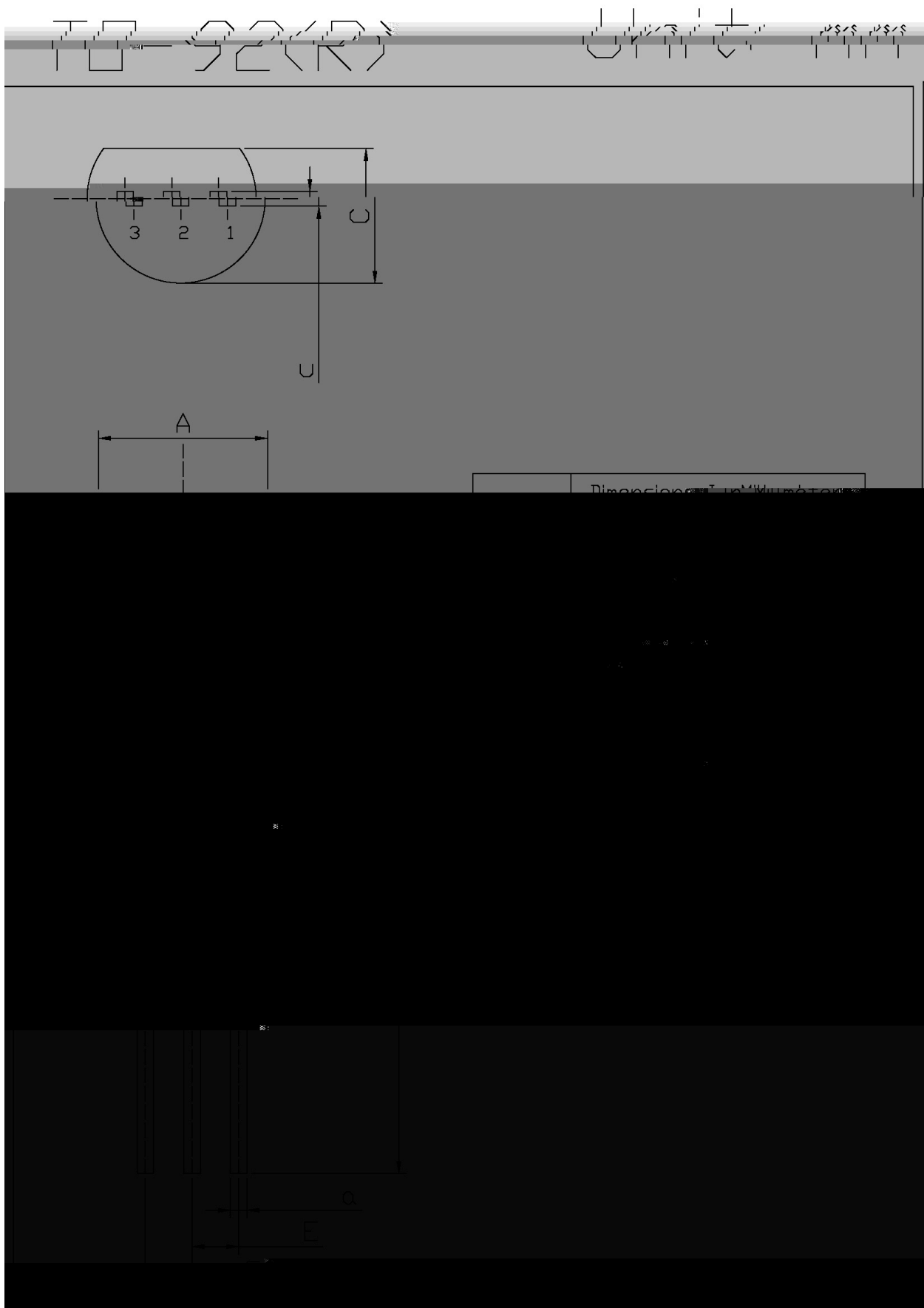
PIN1 Emitter      PIN 2 Base      PIN 3 Collector

## / $h_{FE}$ Classifications & Marking

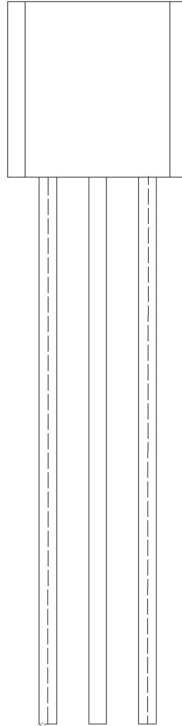
| $h_{FE}$ Classifications<br>Symbol | A       | B       | C   | D | E |
|------------------------------------|---------|---------|-----|---|---|
| $h_{FE}$ Range                     | 110 165 | 150 225 | 202 |   |   |

| Parameter                      | Symbol    | Rating | Unit |
|--------------------------------|-----------|--------|------|
| Collector to Base Voltage      | $V_{CBO}$ | 28     | V    |
| Collector to Emitter Voltage   | $V_{CEO}$ | 20     | V    |
| Emitter to Base Voltage        | $V_{EBO}$ | 6.0    | V    |
| Collector Current - Continuous | $I_C$     | 200    | mA   |
| Base Current - Continuous      | $I_B$     | 200    | mA   |
| Collector Power Dissipation    | $P_c$     | 500    | mW   |
| Junction Temperature           | $T_j$     | 150    |      |

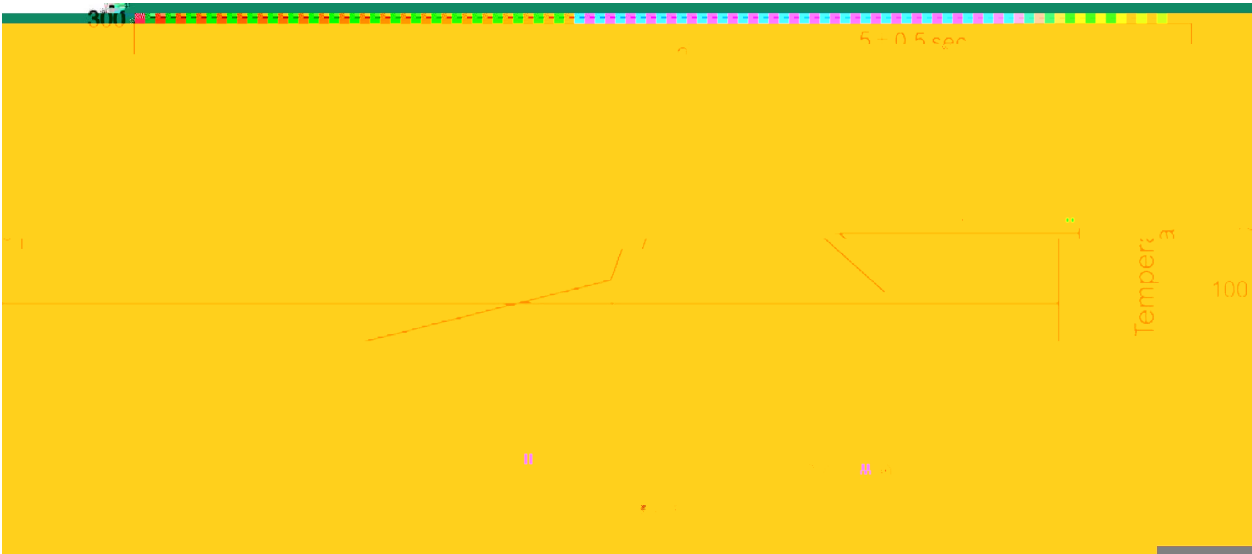
## / Package Dimensions



**/ Marking Instructions**



(     ) / Temperature Profile for Dip Soldering(Pb-Free)



- 1

25   150

60   90sec;

2

255   5

5   0.5sec;

3

2   10   /sec.
- Note:  
1.Preheating:25~150   , Time:60~90sec.  
2.Peak Temp.:255   5   , Duration:5   0.5sec.  
3. Cooling Speed: 2~10   /sec.

/ Resistance to Soldering Heat Test Conditions

270   5                      10   1 sec.                      Temp.:270±5                      Time:10±1 sec

/ Packaging SPEC.

/ BULK